



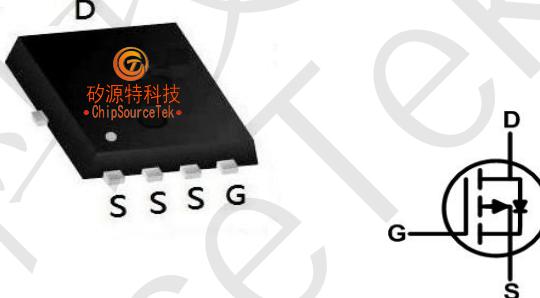
- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

CST100N85F Product Summary



BVDSS	RDS(ON)	ID
85V	4.3mΩ	100A

CST100N85F PRPAK5X6 Pin Configuration

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	85	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $T_c=25^\circ\text{C}$	I_D	100	A
$T_c=100^\circ\text{C}$		63.3	
Pulsed Drain Current ¹	I_{DM}	400	A
Single Pulse Avalanche Energy ²	EAS	273.8	mJ
Total Power Dissipation	P_D	107.8	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	60	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	1.16	°C/W



N-Ch 85V Fast Switching MOSFETs

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	85	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	I_{DSS}	$V_{\text{DS}} = 85\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-Source on-Resistance ⁴	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	4.3	5.6	$\text{m}\Omega$
Forward Transconductance ⁴	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 20\text{A}$	-	57.8	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	4645	-	pF
Output Capacitance	C_{oss}		-	673	-	
Reverse Transfer Capacitance	C_{rss}		-	41	-	
Gate Resistance	R_g	$f = 1\text{MHz}$	-	2.0	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 40\text{V}, I_D = 20\text{A}$	-	61.3	-	nC
Gate-Source Charge	Q_{gs}		-	21	-	
Gate-Drain Charge	Q_{gd}		-	11	-	
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 40\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	16.5	-	ns
Rise Time	t_r		-	51.8	-	
Turn-off Delay Time	$t_{\text{d(off)}}$		-	37.1	-	
Fall Time	t_f		-	8.2	-	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	69	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	141	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current $T_c = 25^\circ\text{C}$	I_S	-	-	-	100	A

Notes:

- Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX}) = 150^\circ\text{C}$
- The EAS data shows Max. rating. The test condition is $V_{\text{DD}} = 50\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.4\text{mH}, I_{\text{AS}} = 37\text{A}$
- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper. The value in any given application depends on the user's specific board design.
- The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
- This value is guaranteed by design hence it is not included in the production test.



CST100N85F Typical Characteristics

N-Ch 85V Fast Switching MOSFETs

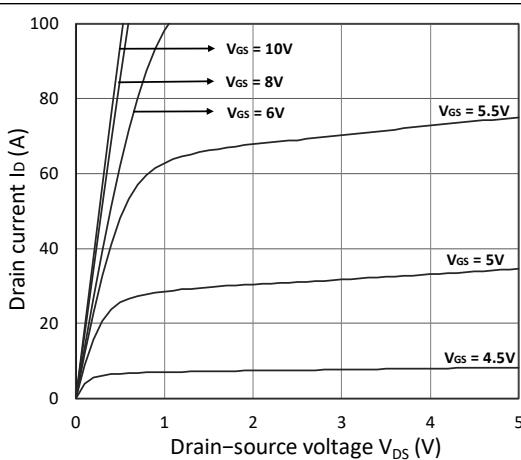


Figure 1. Output Characteristics

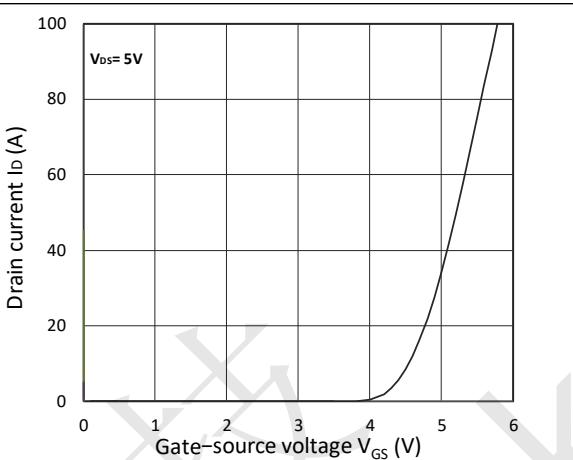


Figure 2. Transfer Characteristics

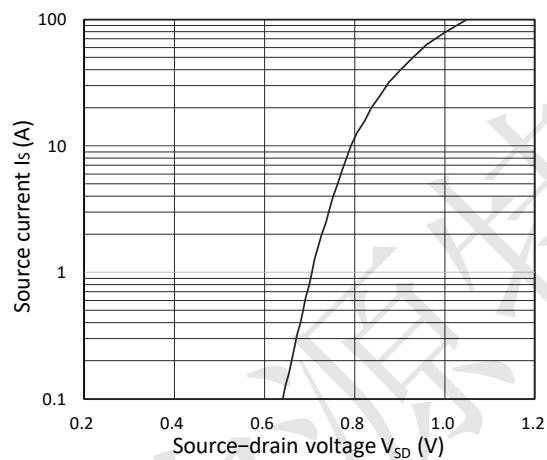
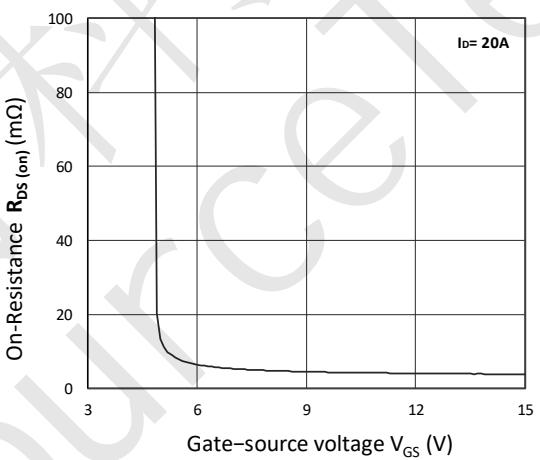
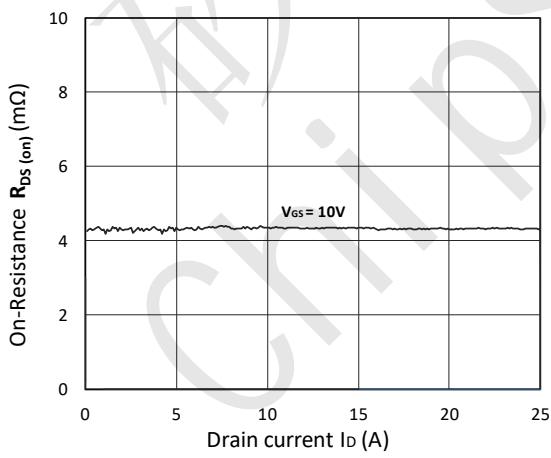
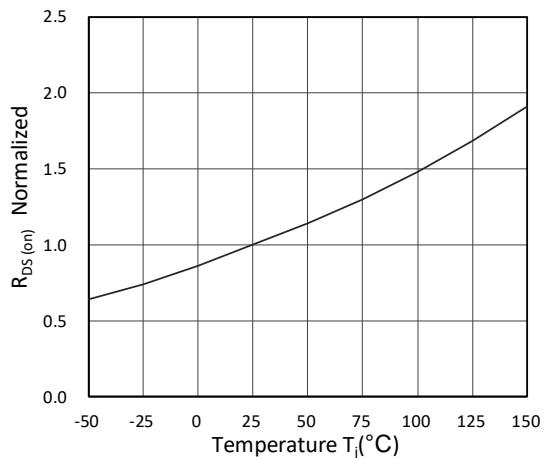


Figure 3. Forward Characteristics of Reverse

Figure 4. $R_{DS(on)}$ vs. V_{GS} Figure 5. $R_{DS(on)}$ vs. I_D Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



N-Ch 85V Fast Switching MOSFETs

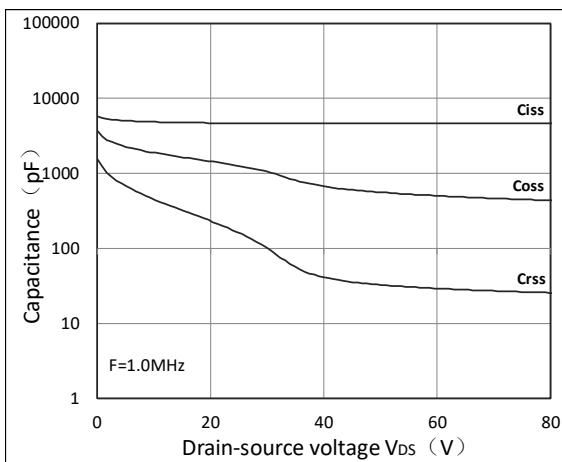


Figure 7. Capacitance Characteristics

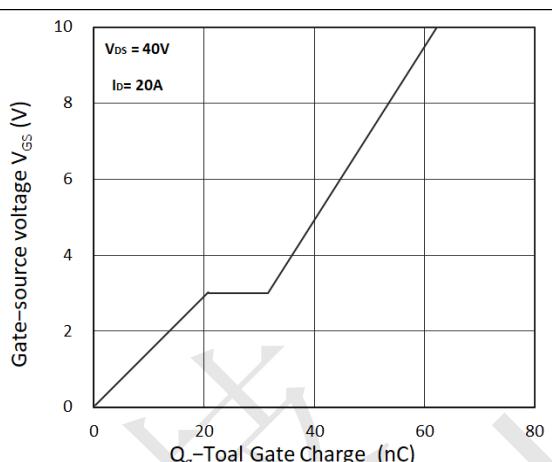


Figure 8. Gate Charge Characteristics

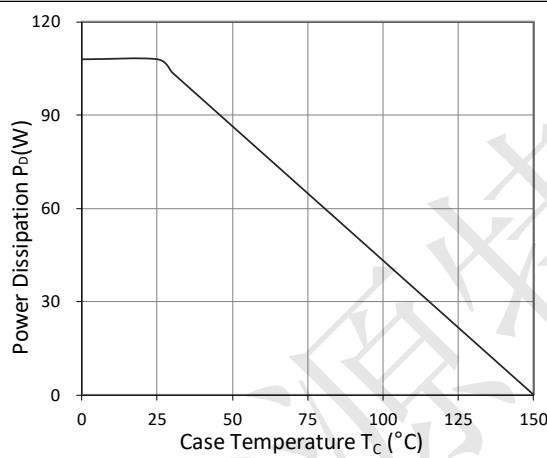


Figure 9. Power Dissipation

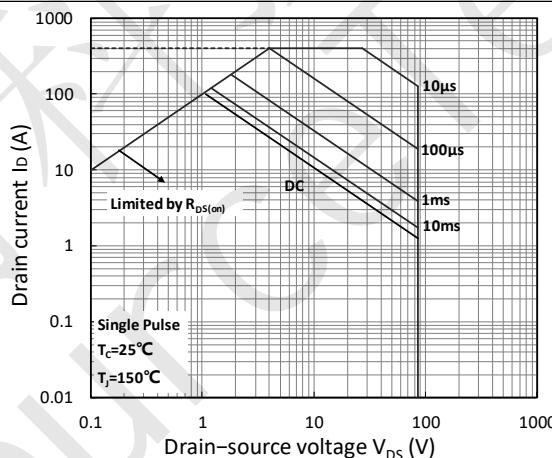


Figure 10. Safe Operating Area

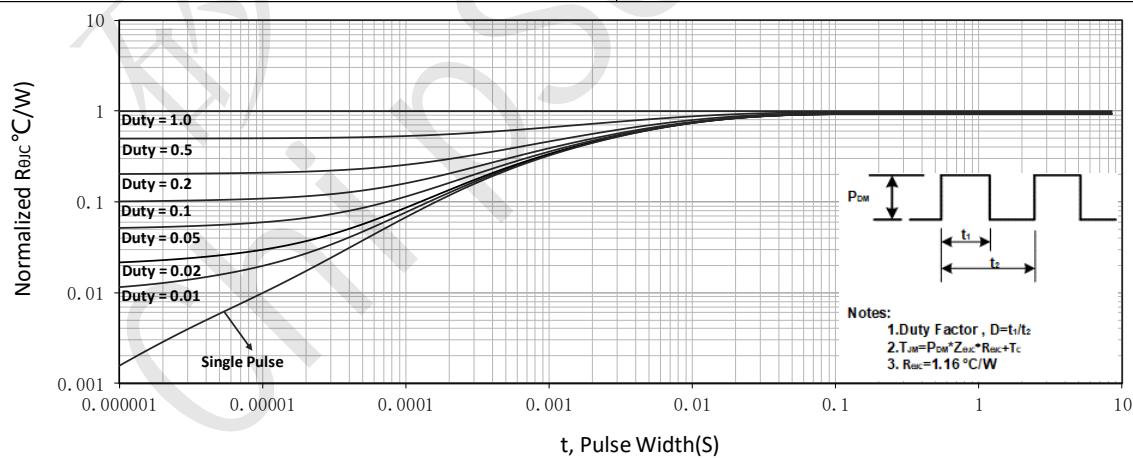
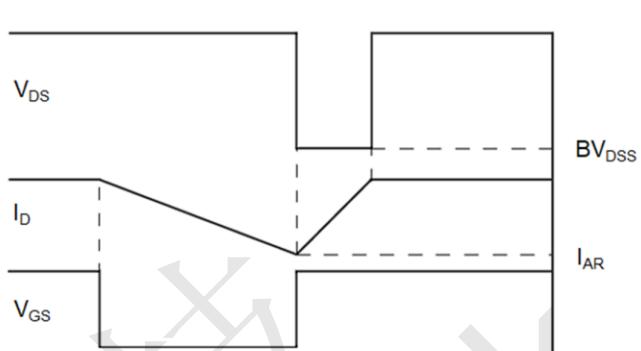
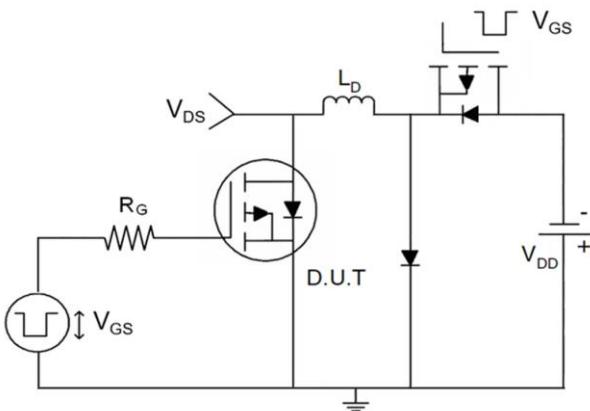
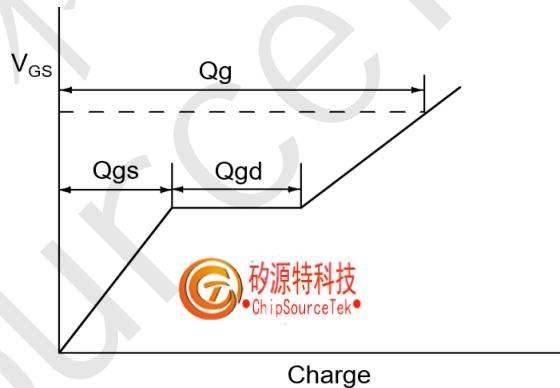
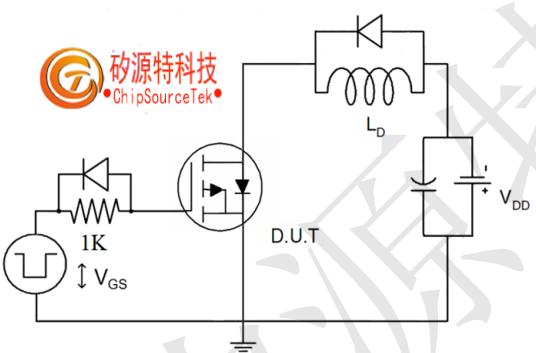


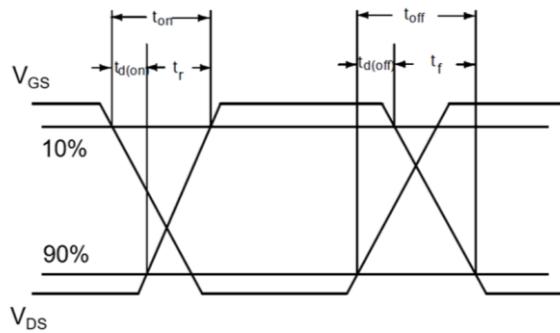
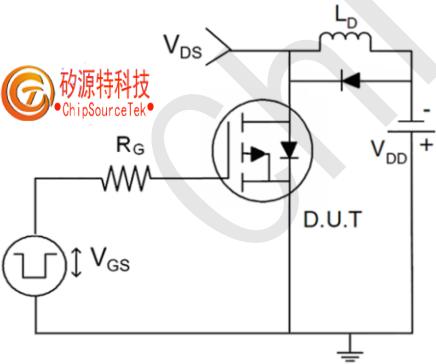
Figure 11. Normalized Maximum Transient Thermal Impedance

1) E_{AS} Test Circuits

2) Gate Charge Test Circuit

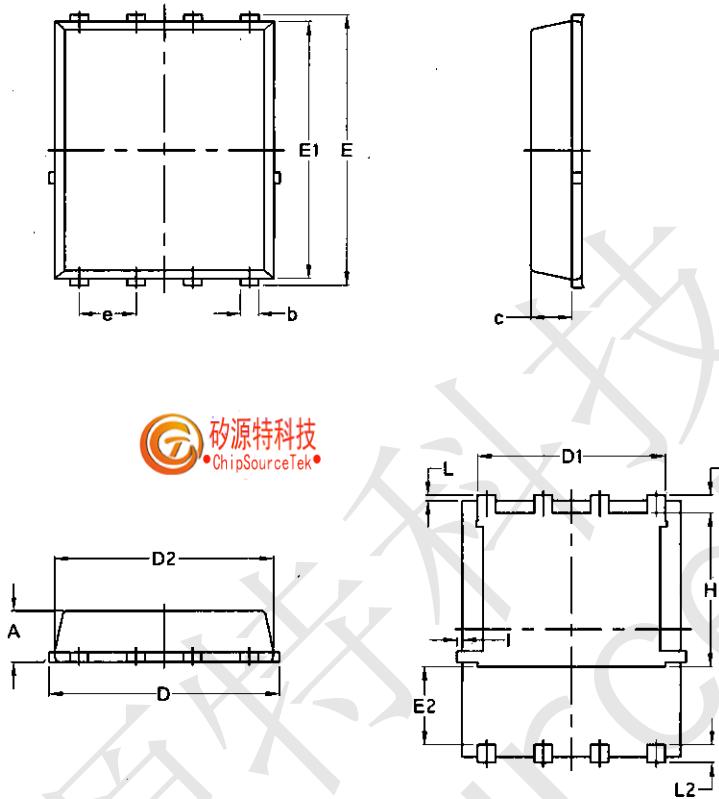


3) Switch Time Test Circuit





CST100N85F Package Mechanical Data-DFN5*6-8L -Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070